## **ON Semiconductor**

## Is Now



To learn more about onsemi™, please visit our website at www.onsemi.com

onsemi and ONSEMI. and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. onsemi reserves the right to make changes at any time to any products or information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/ or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi does not convey any license under any of its intellectual property rights nor the rights of others. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use onsemi products for any such unintended or unauthorized application,



ON Semiconductor®

# FQT3P20

## P-Channel QFET® MOSFET

-200 V, -0.67 A, 2.7 Ω

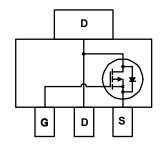
## **Description**

This P-Channel enhancement mode power MOSFET is produced using ON Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, audio amplifier, DC motor control, and variable switching power applications.

#### **Features**

- -0.67 A, -200 V,  $R_{DS(on)}$  = 2.7  $\Omega$  (Max.) @V  $_{GS}$  = 10 V,  $I_{D}$  = 0.335 A
- Low Gate Charge (Typ. 6.0 nC)
- Low Crss (Typ. 7.5 pF)





# **Absolute Maximum Ratings** $T_C = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter		FQT3P20TF	Unit
$V_{DSS}$	Drain-Source Voltage		-200	V
I <sub>D</sub>	Drain Current - Continuous (T <sub>C</sub> = 25°	C)	-0.67	Α
	- Continuous (T <sub>C</sub> = 70°	C)	-0.53	Α
I <sub>DM</sub>	Drain Current - Pulsed	(Note 1)	-2.7	Α
V <sub>GSS</sub>	Gate-Source Voltage		± 30	V
E <sub>AS</sub>	Single Pulsed Avalanche Energy	(Note 2)	150	mJ
I <sub>AR</sub>	Avalanche Current	(Note 1)	-0.67	Α
E <sub>AR</sub>	Repetitive Avalanche Energy	(Note 1)	0.25	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	-5.5	V/ns
$P_D$	Power Dissipation (T <sub>C</sub> = 25°C)		2.5	W
	- Derate above 25°C		0.02	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Rar	nge	-55 to +150	°C
T <sub>L</sub>	Maximum lead temperature for soldering 1/8" from case for 5 seconds	purposes,	300	°C

### **Thermal Characteristics**

Symbol	Parameter	FQT3P20TF	Unit
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	50	°C/W

Package Marking and Ordering Information	mation
--	--------

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FQT3P20	FQT3P20TF	SOT-223	13"	12 mm	2500 units

## **Electrical Characteristics**

 $T_C = 25$ °C unless otherwise noted.

Parameter	Test Conditions	Min	Тур	Max	Unit			
Off Characteristics								
Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_{D} = -250 \mu\text{A}$	-200			V			
Breakdown Voltage Temperature Coefficient	$I_D$ = -250 $\mu$ A, Referenced to 25°C		-0.18		V/°C			
Zoro Cata Valtaga Drain Current	V <sub>DS</sub> = -200 V, V <sub>GS</sub> = 0 V			-1	μΑ			
Zero Gate Voltage Drain Current	V <sub>DS</sub> = -160 V, T <sub>C</sub> = 125°C			-10	μΑ			
Gate-Body Leakage Current, Forward	$V_{GS} = -30 \text{ V}, V_{DS} = 0 \text{ V}$			-100	nA			
Gate-Body Leakage Current, Reverse	V <sub>GS</sub> = 30 V, V <sub>DS</sub> = 0 V			100	nA			
1	Drain-Source Breakdown Voltage Breakdown Voltage Temperature Coefficient Zero Gate Voltage Drain Current Gate-Body Leakage Current, Forward	$ \begin{array}{cccccccccccccccccccccccccccccccccccc$	$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$			

#### **On Characteristics**

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	-3.0		-5.0	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	$V_{GS} = -10 \text{ V}, I_D = -0.335 \text{ A}$		2.06	2.7	Ω
9 <sub>FS</sub>	Forward Transconductance	$V_{DS} = -40 \text{ V}, I_{D} = -0.335 \text{ A}$		0.7		S

## **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = -25 V, V <sub>GS</sub> = 0 V,	 190	250	pF
Coss	Output Capacitance	f = 1.0 MHz	 45	60	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		 7.5	10	pF

## **Switching Characteristics**

	•				
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> = -100 V, I <sub>D</sub> = -2.8 A,	 8.5	25	ns
t <sub>r</sub>	Turn-On Rise Time	$R_G = 25 \Omega$	 35	80	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	G -	 12	35	ns
t <sub>f</sub>	Turn-Off Fall Time	(Note 4)	 25	60	ns
$Q_g$	Total Gate Charge	V <sub>DS</sub> = -160 V, I <sub>D</sub> = -2.8 A,	 6.0	8.0	nC
Q <sub>gs</sub>	Gate-Source Charge	V <sub>GS</sub> = -10 V	 1.7		nC
Q <sub>gd</sub>	Gate-Drain Charge	(Note 4)	 2.9		nC

### **Drain-Source Diode Characteristics and Maximum Ratings**

		•				
Is	Maximum Continuous Drain-Source Diode Forward Current				-0.67	Α
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode Forward Current				-2.7	Α
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>S</sub> = -0.67 A			-5.0	V
trr	Reverse Recovery Time	$V_{GS} = 0 \text{ V}, I_{S} = -2.8 \text{ A},$		100		ns
Qrr	Reverse Recovery Charge	$dI_F / dt = 100 A/\mu s$		0.34		μС

- **Notes:**1. Repetitive Rating: Pulse width limited by maximum junction temperature 2. L = 500mH, I<sub>AS</sub> = -0.67A, V<sub>DD</sub> = -50V, R<sub>G</sub> = 25 Ω, Starting T<sub>J</sub> = 25°C 3. I<sub>SD</sub>  $\leq$  -2.8A, di/dt  $\leq$  300A/μs, V<sub>DD</sub>  $\leq$  BV<sub>DSS</sub>, Starting T<sub>J</sub> = 25°C 4. Essentially independent of operating temperature

## **Typical Characteristics**

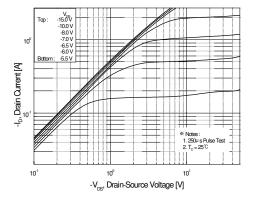


Figure 1. On-Region Characteristics

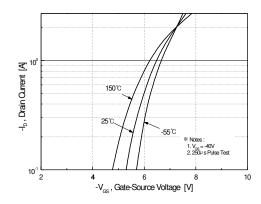


Figure 2. Transfer Characteristics

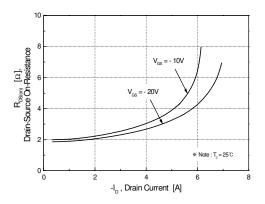


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

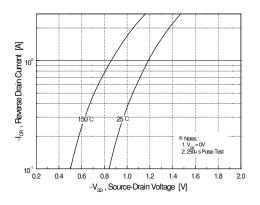


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

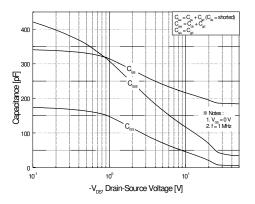


Figure 5. Capacitance Characteristics

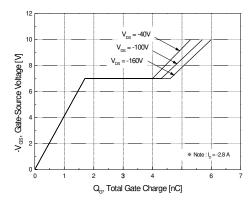


Figure 6. Gate Charge Characteristics

## Typical Characteristics (Continued)

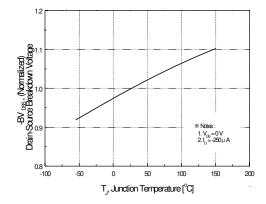


Figure 7. Breakdown Voltage Variation vs. Temperature

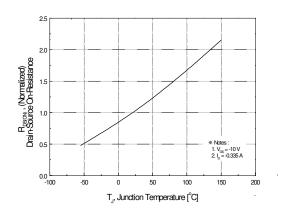


Figure 8. On-Resistance Variation vs. Temperature

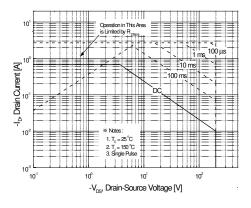


Figure 9. Maximum Safe Operating Area

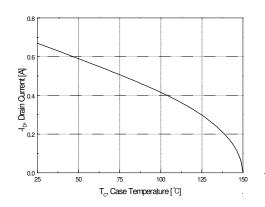


Figure 10. Maximum Drain Current vs. Case Temperature

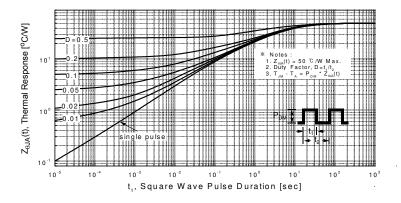


Figure 11. Transient Thermal Response Curve

Figure 12. Gate Charge Test Circuit & Waveform

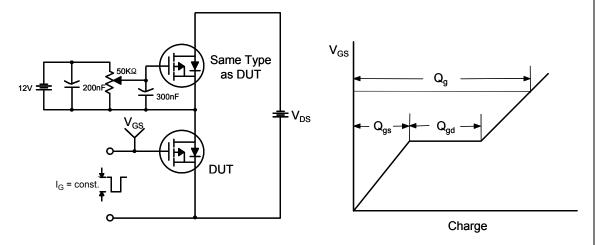


Figure 13. Resistive Switching Test Circuit & Waveforms

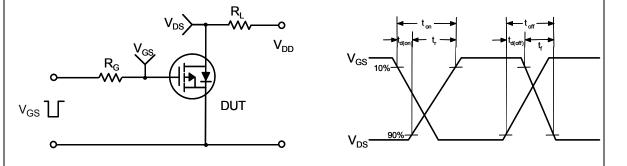


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms

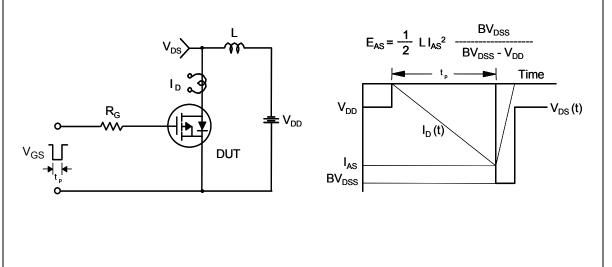
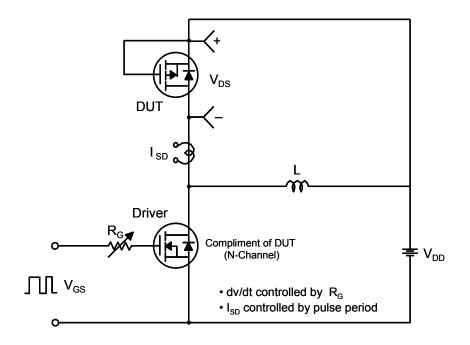
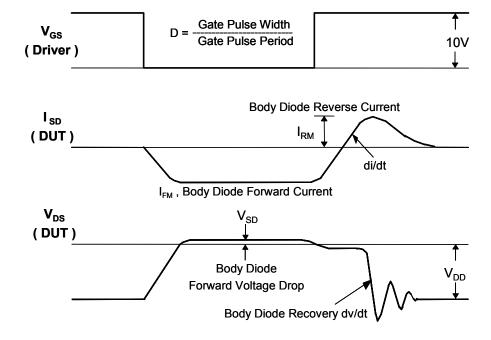


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms





### **Mechanical Dimensions**

# SOT-223 4L

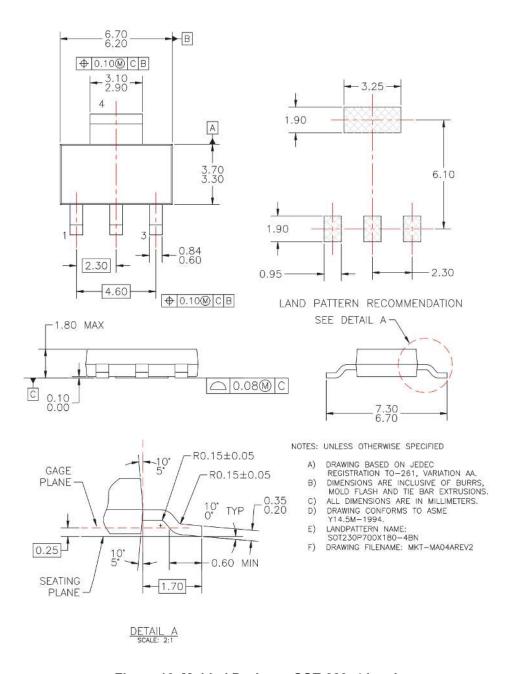


Figure 16. Molded Package, SOT-223, 4 Lead

Package drawings are provided as a service to customers considering ON Semiconductor components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a ON Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Semiconductor's worldwide terms and conditions, specif-ically the warranty therein, which covers ON Semiconductor products.

Dimension in Millimeters

ON Semiconductor and in are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at <a href="www.onsemi.com/site/pdf/Patent-Marking.pdf">www.onsemi.com/site/pdf/Patent-Marking.pdf</a>. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hol

#### **PUBLICATION ORDERING INFORMATION**

#### LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800-282-9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910

Phone: 421 33 790 2910

Japan Customer Focus Center

Phone: 81–3–5817–1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative